06.05.2014

OS-PCN-2014-008-A1

!! UPDATE !!

Dear Customer,

please find attached our OSRAM OS PCN:

the previous OS-PCN-2014-008-A now affects further types / other changes, please see next page.

"Introduction of additional 6" wafer production for InGaAIP TF dies – Part 2"

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **06.06.2014**.
- OSRAM OS aligns with the widely-recognized JEDEC STANDARD "JESD46-B", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".

Your prompt reply will help OSRAM OS to assure a smooth and well executed transition. If OSRAM OS does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Please direct your inquiry to your local Sales office.



06.05.2014

OS-PCN-2014-008-A1

!! UPDATE !!

Updated Information in ITALIC/ BLUE TYPE	
Original PCN(Master) see PCN N° OS-PCN-2014-008-A dated	

SUBJECT OF CHANGE:	Introduction of additional 6" v InGaAIP TF dies – Part 2	vafer production for
PRODUCTS AFFECTED:	For a detailed overview of the affected products, please refer to the attached product list.	
	Now including additional LEE lighting devices .	D's as well as general
	Revised product list – som deleted from the product li dies. These dies are not af 6" wafer production in this	st. They were using 1mm fected of the change to
REASON OF CHANGE:	Secure continuous supply - Io Increase automotive capacity demand.	
DESCRIPTION OF CHANGE:	For a detailed overview pleas 1_cip_OS-PCN-2014-008-A	
PRODUCT IDENTIFICATION:	Date code	
TIME SCHEDULE:	Final qualification report	300µm die final report available
		500µm die final report available
	Samples available	On request
	Production release	Q2 / 2014*
	Start of delivery	Q2 / 2014*

*or earlier if released by customer



ASSESSMENT:	Physical properties <u>remain unchanged</u> Electro-optical parameters <u>remain unchanged</u> . Chips from 6" wafers are <u>fully miscible</u> with chips from 4" wafers

DOCUMENTATION:	1_cip_OS-PCN-2014-008-A1
	2_cip_OS-PCN-2014-008-A1
	3_cip_OS-PCN-2014-008-A1



06.05.2014

OS-PCN-2014-008-A1

!! UPDATE !!

Customer Approval Form

Introduction of additional 6" wafer production for InGaAIP TF dies – Part 2

Please list product(s) affected in your application(s):
Please check the appropriate box below:
□ We agree with the proposed change and accept start of shipment upon availability of new version.
□ We have objections:
□ We need more information:
□ We need the following samples:
Sender: Company: Name:
Address/Location:
Signature Date
Please return to your Sales partner: Name:
Address/Location:
TELEPHONE FAX FAX



Г

Products Affected by Product Change Notification

Number: OS-PCN-2014-008-A1 Name: Introduction of additional 6" wafer production for InGaAIP TF dies – Part 2 Release Date: 5/6/2014 Response Due Date: 6/6/2014 Implementation Date: 7/6/2014

Product	Q Number	QNumber Description	Part Number
GR DASPA1.23	Q65111A4399	GR DASPA1.23-FRFT-26-1-100-R18	GR DASPA1.23-FRFT-26-1
	Q65111A4400	GR DASPA1.23-FQFS-26-1-100-R18	GR DASPA1.23-FQFS-26-1
	Q65111A4407	GR DASPA1.23-FUGQ-23-1-100-R18	GR DASPA1.23-FUGQ-23-1
	Q65111A4755	GR DASPA1.23-FQFS-46-1-100-R18	GR DASPA1.23-FQFS-46-1
GY DASPA1.23	Q65111A4404	GY DASPA1.23-ETFP-36-1-100-R18	GY DASPA1.23-ETFP-36-1
	Q65111A4492	GY DASPA1.23-FPFR-36-1-100-R18	GY DASPA1.23-FPFR-36-1
	Q65111A4493	GY DASPA1.23-FQFS-36-1-100-R18	GY DASPA1.23-FQFS-36-1
LYYYG6SF	Q65110A6404	LYYYG6SF-DAEA-45-0-50-R18-Z-HE	LYYYG6SF-DAEA-45-Z-HE
	Q65110A6857	LYYYG6SF-CBDB-35-0-50-R18-Z	LYYYG6SF-CBDB-35-Z
	Q65110A8529	LYYYG6SF-CADB-45-0-50-R18-Z	LYYYG6SF-CADB-45-Z
	Q65110A8564	LYYYG6SF-CBDB-45-0-50-R18-Z	LYYYG6SF-CBDB-45-Z
	Q65111A1180	LYYYG6SF-DAEA-45-0-50-R18-Z-XX	LYYYG6SF-DAEA-45-Z-XX
SFH 4226	Q65111A0102	SFH 4226	SFH 4226
SFH 4571	Q65111A4284	SFH 4571	SFH 4571